

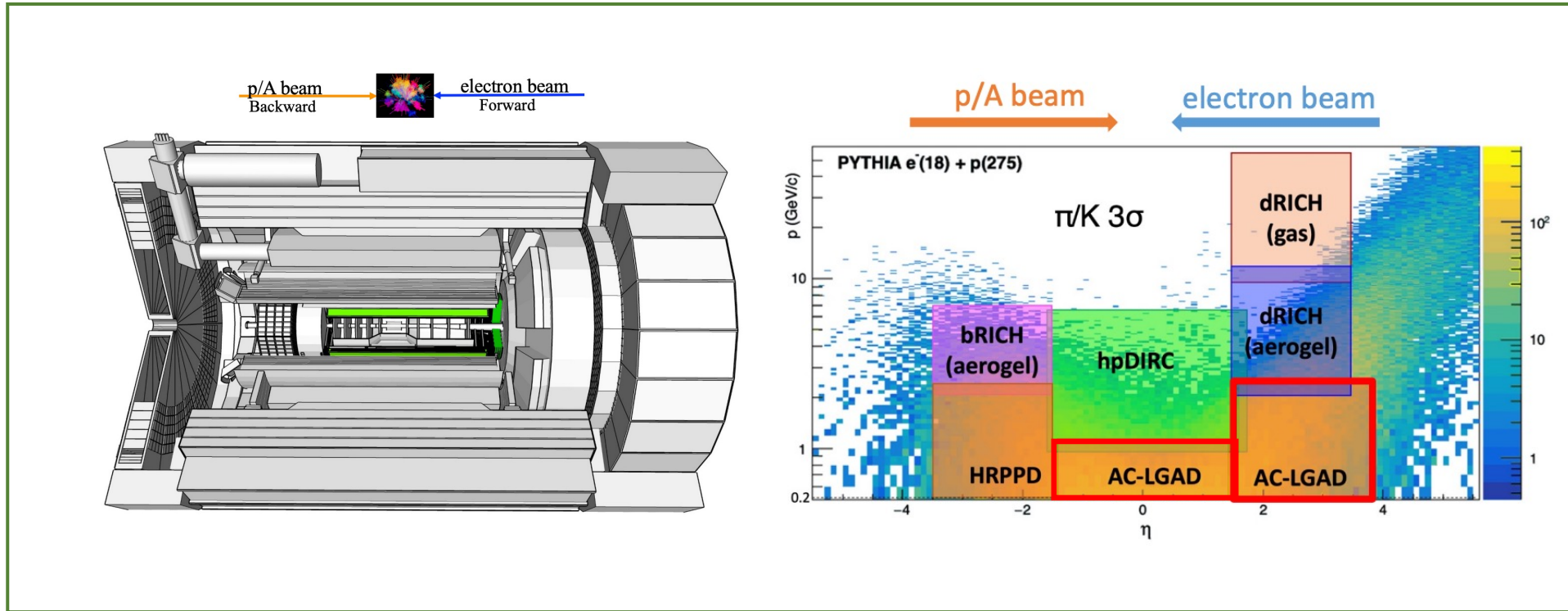
# ToF External Tracking Resolution Requirements

Shirsendu Nanda  
(On behalf of ToF team)

University of Illinois at Chicago (UIC)

ePIC Collaboration Meeting  
Argonne National Laboratory

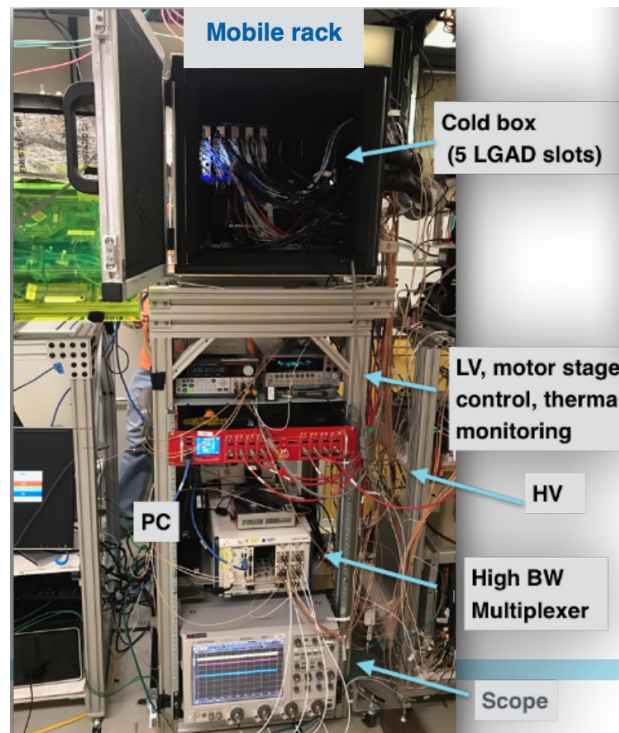
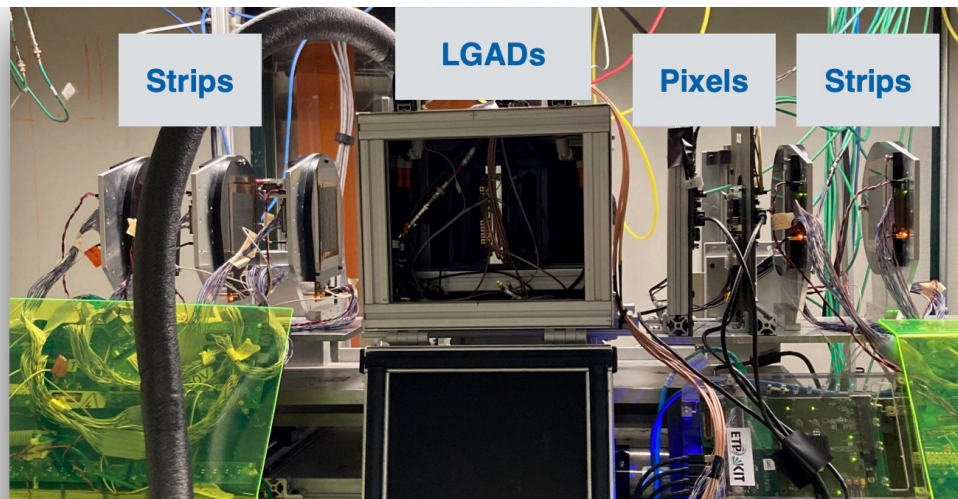
# Specifications of ePIC AC-LGAD ToF detectors in EIC:



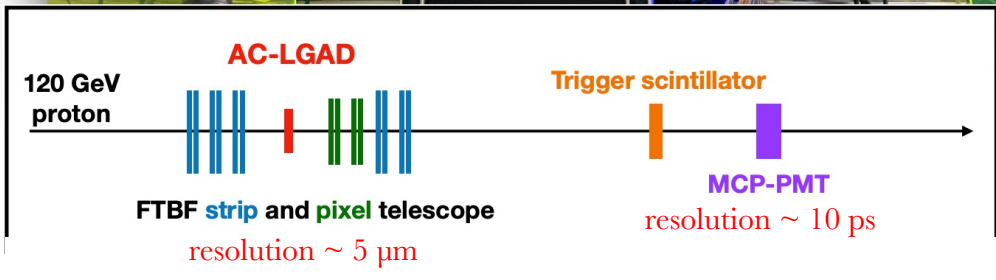
- **ToF** : PID capabilities below the threshold of Cherenkov PID detectors

	Angular accept.	Channel size (mm <sup>2</sup> )	Timing Resolution	Spatial resolution	Material budget
Barrel ToF	$-1.4 < \eta < 1.4$	0.5*10	35 ps	30 $\mu\text{m}$ in $\varphi$	0.01 X0
Forward ToF	$1.5 < \eta < 3.5$	0.5*0.5	25 ps	30 $\mu\text{m}$ in x and y	0.05 X0

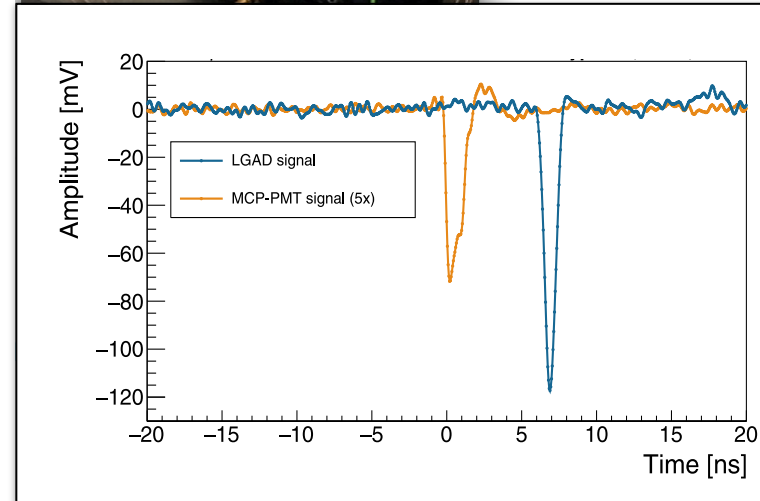
# Fermilab test beam setup for AC-LGADs:



Record 20k events during 4s spill  
**8-channel oscilloscope, 2 GHz, 10 GSa/s**

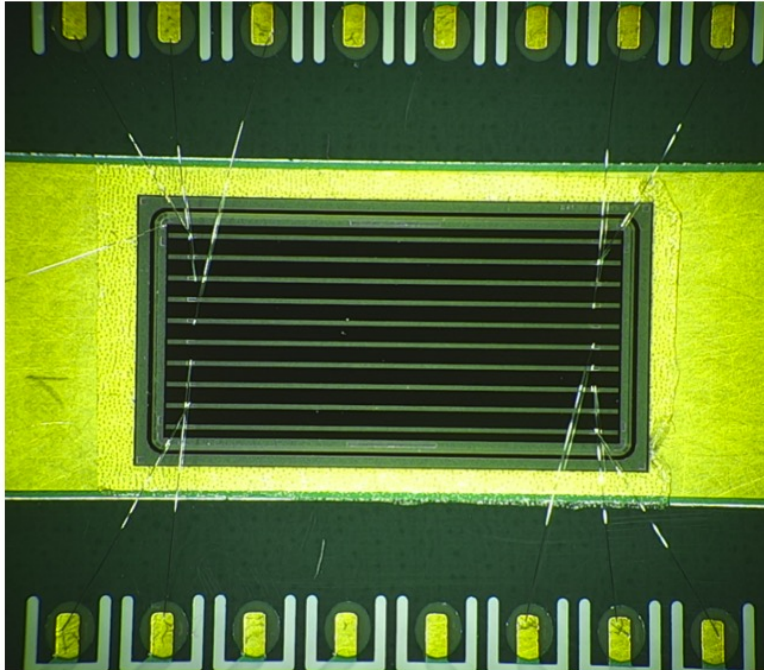


- 120 GeV primary proton beam from main injector
- AC-LGAD and MCP-PMT waveforms were recorded in the oscilloscope
- Stable temperature of 20<sup>0</sup> C maintained inside the cooling block
- Optimal bias is a few volts below the breakdown (stable noise from the channels)
- Sensor alignment based on position of sensor along beamline and rotation around beam



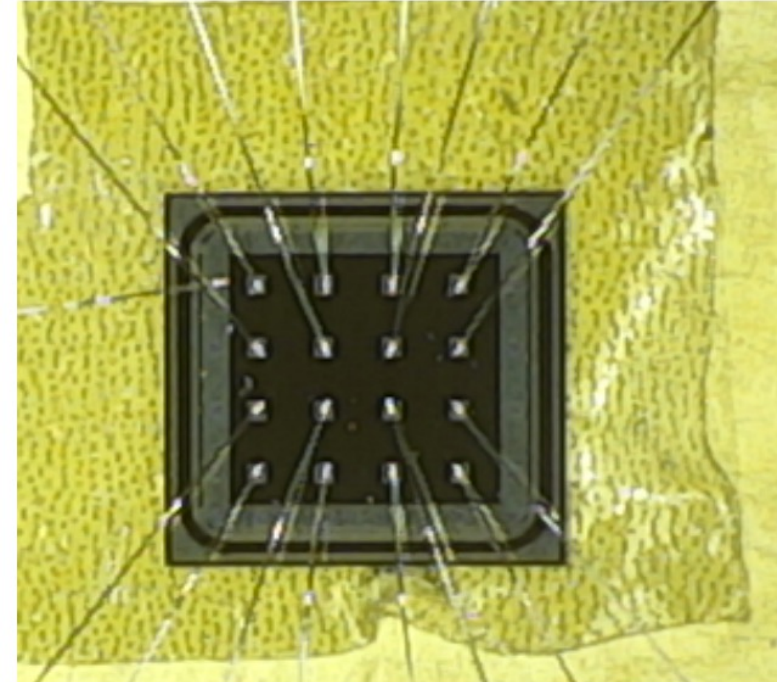
# Large area AC-LGAD sensors in test beam campaign 2023:

HPK strip sensor



10 mm length, 500  $\mu\text{m}$  pitch, 50  $\mu\text{m}$  metal width, 50  $\mu\text{m}$  thickness, 1600  $\Omega/\square$  resistivity, and 240  $\text{pF}/\text{mm}^2$  capacitance

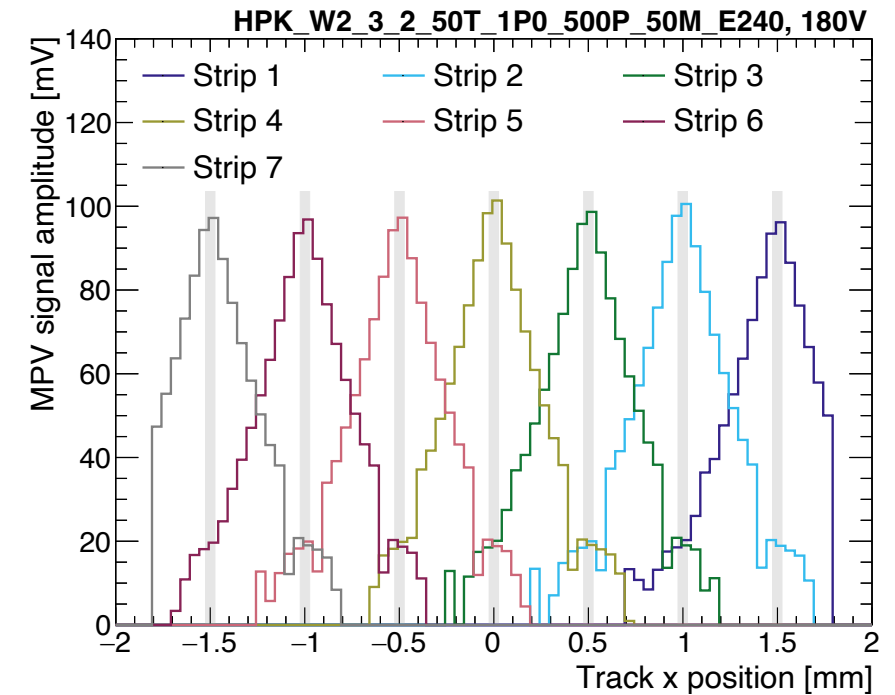
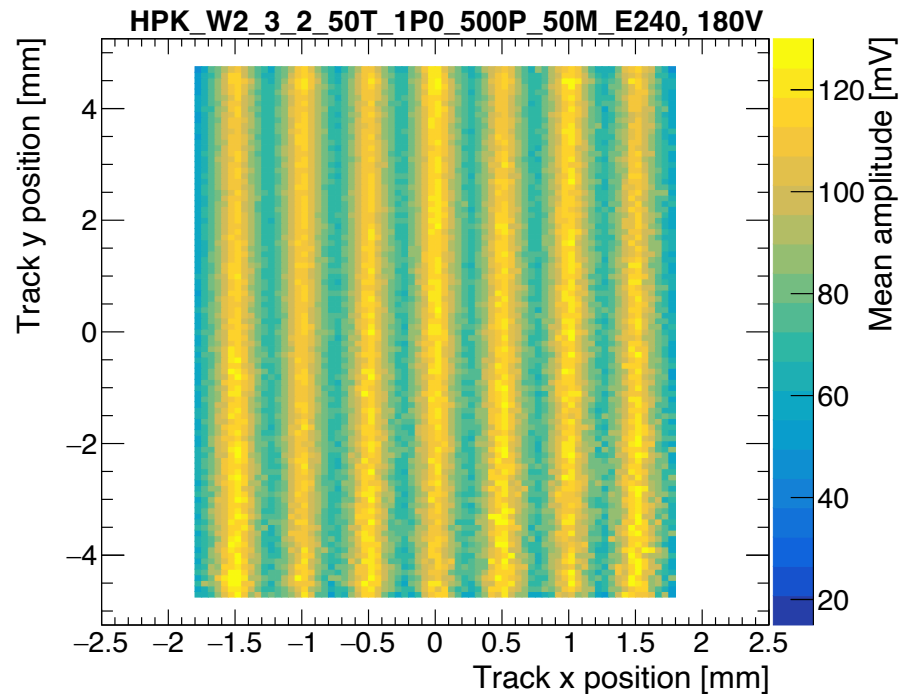
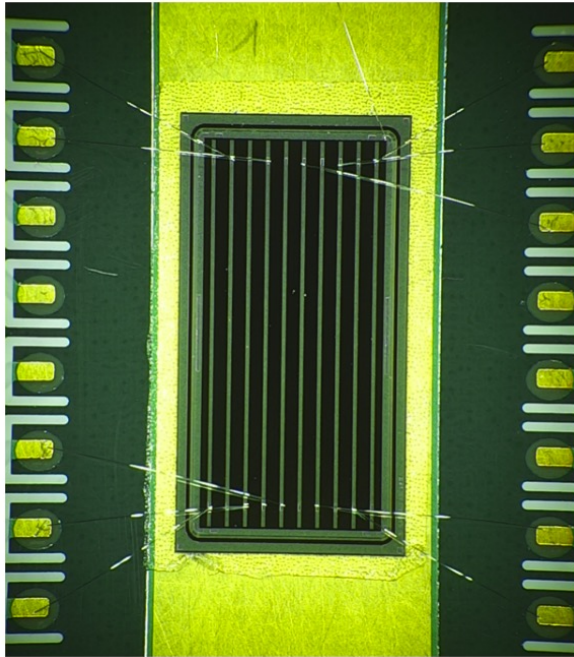
HPK 4  $\times$  4 pixel sensor



500  $\times$  500  $\mu\text{m}$  pitch, 20  $\mu\text{m}$  thickness, 150  $\mu\text{m}$  metal width, 400  $\Omega/\square$  resistivity, and 600  $\text{pF}/\text{mm}^2$  capacitance

# Large area AC-LGAD strip sensor :

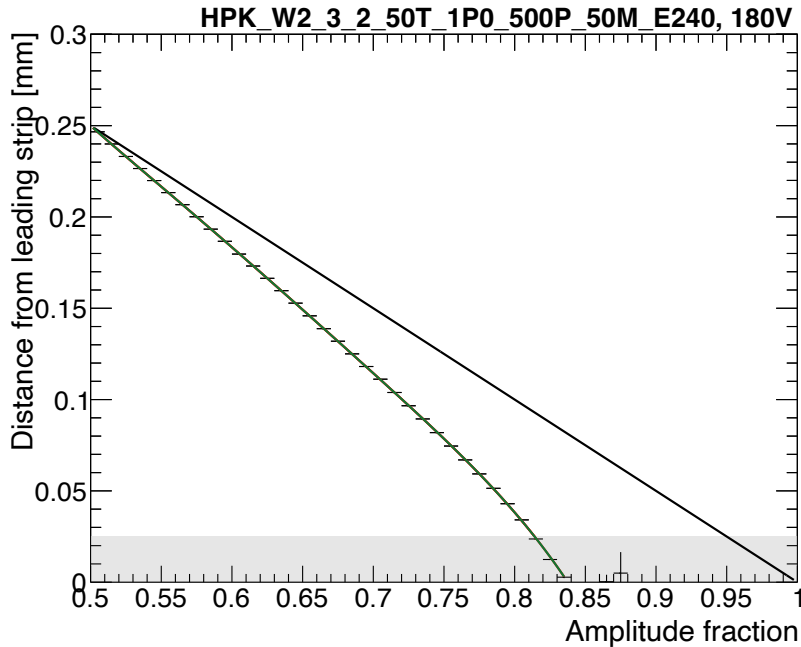
10 mm length, 500  $\mu\text{m}$  pitch, 50  $\mu\text{m}$  metal width, 50  $\mu\text{m}$  thickness, 1600  $\Omega/\square$  resistivity, and 240  $\text{pF}/\text{mm}^2$  capacitance



- Signal sharing between strips enables the 'x' position (perpendicular to the strip direction) reconstruction
- Unable to perform the 'y' position (along the strip direction) reconstruction in strip sensor

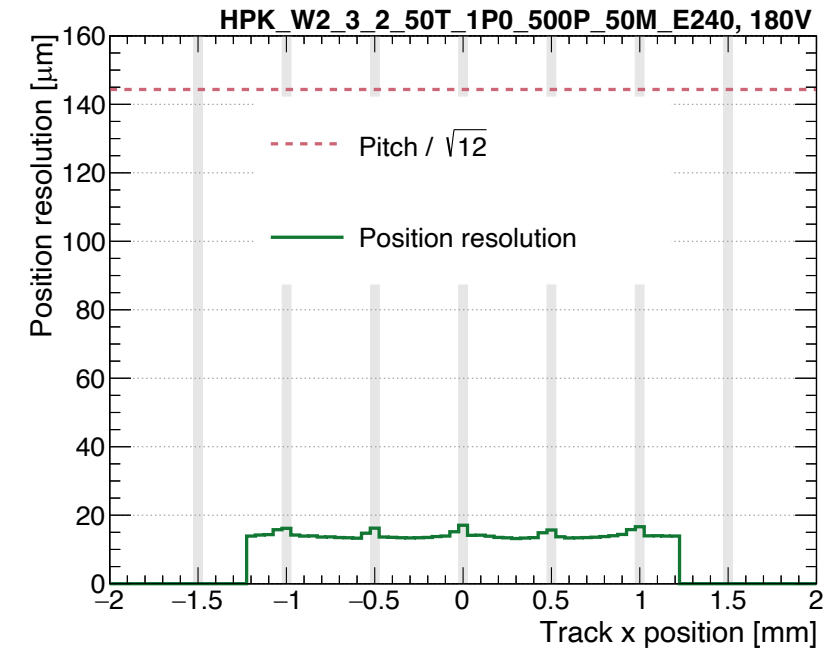
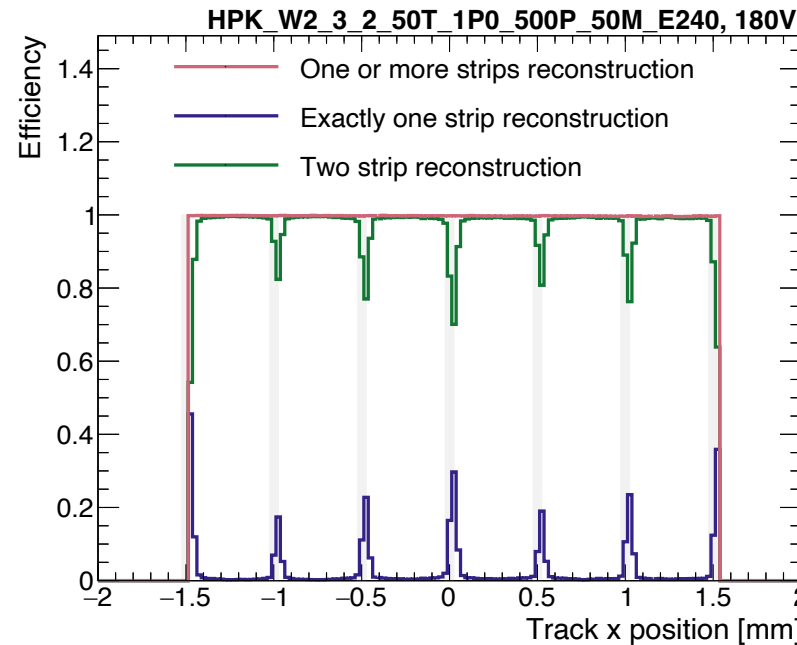
# Spatial resolution in large area AC-LGAD strip sensor :

10 mm length, 500  $\mu\text{m}$  pitch, 50  $\mu\text{m}$  metal width, 50  $\mu\text{m}$  thickness, 1600  $\Omega/\square$  resistivity, and 240 pF/mm<sup>2</sup> capacitance



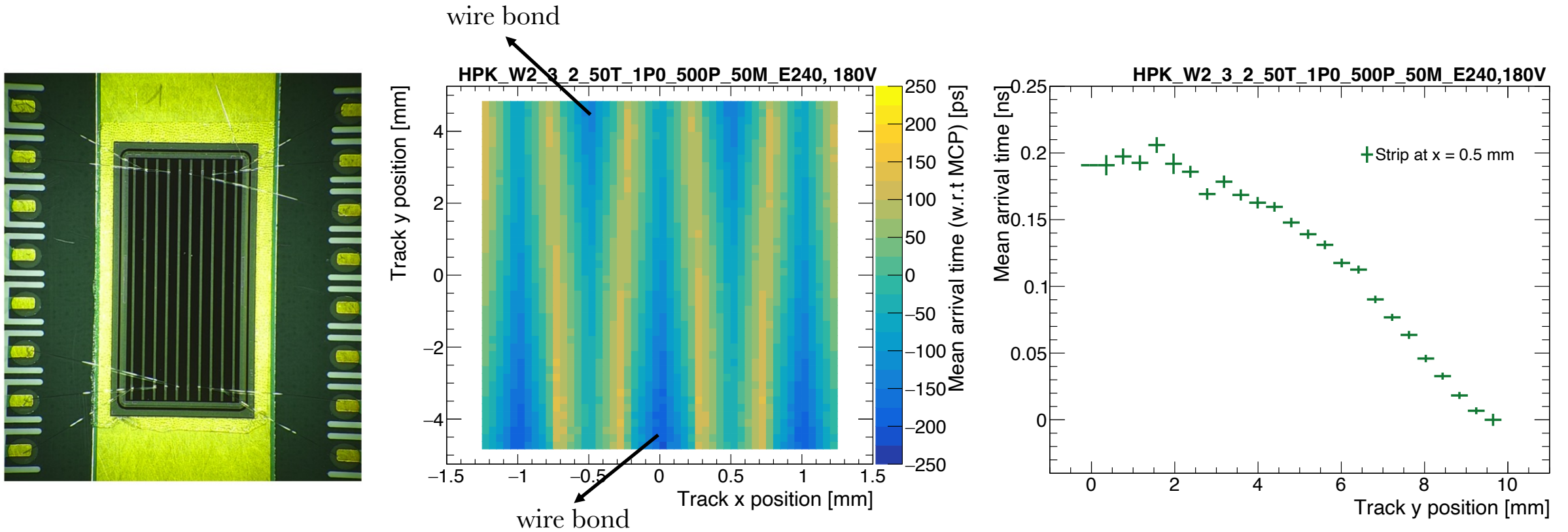
- Amplitude fraction  $f = a1 / (a1 + a2)$  where  $a1$  and  $a2$  are the leading and sub-leading strip amplitudes
- Two-strip reconstruction at gap and one-strip reconstruction on metal

- Efficiency reaches  $\sim 100\%$
- Position resolution  $\sim 12 - 15 \mu\text{m}$



# Time delay in large area AC-LGAD strip sensor :

10 mm length, 500  $\mu\text{m}$  pitch, 50  $\mu\text{m}$  metal width, 50  $\mu\text{m}$  thickness, 1600  $\Omega/\square$  resistivity, and 240 pF/mm<sup>2</sup> capacitance



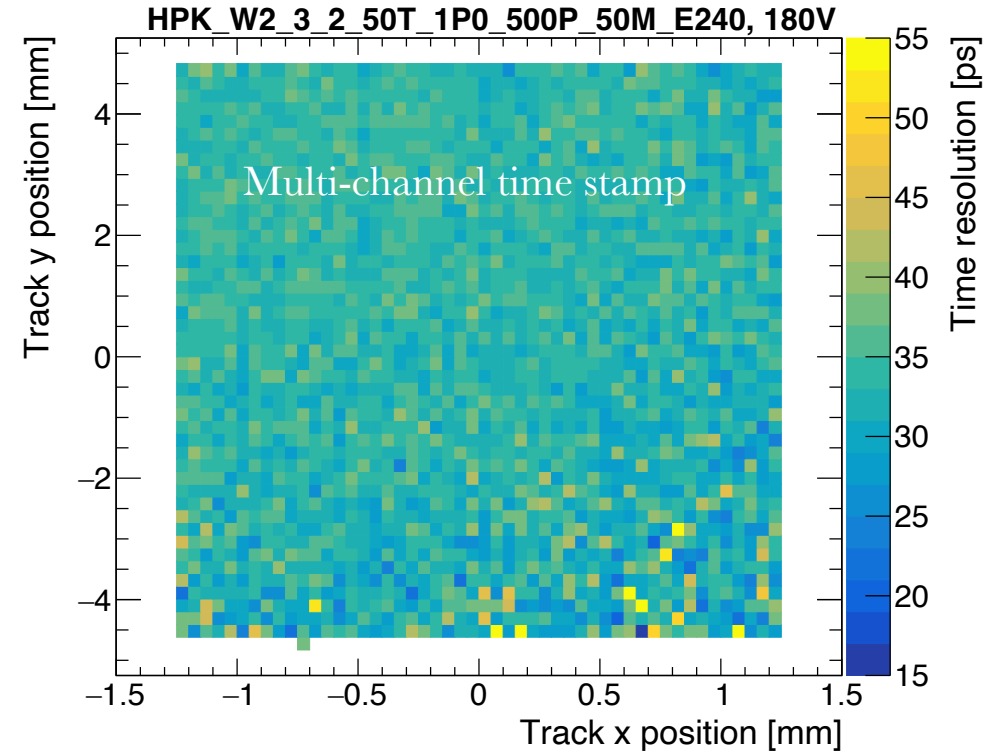
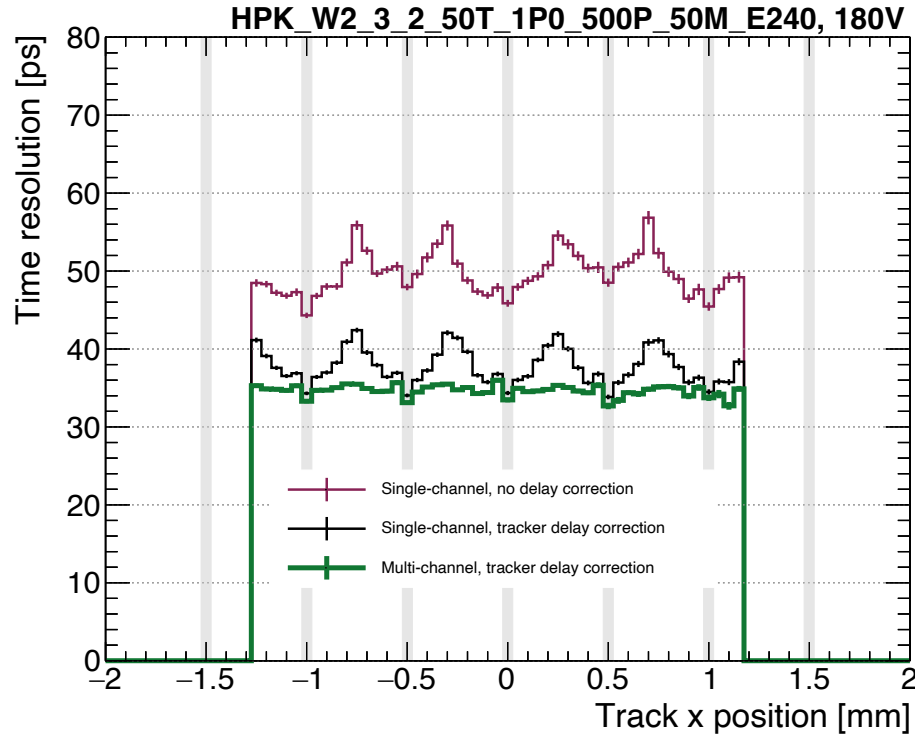
- Due to larger electrodes, distant signals arrival with delays  $O(100 \text{ ps})$
- Position-dependent time delay correction is essential
- Delay map use the resolution of 50  $\mu\text{m}$  for x position and 200  $\mu\text{m}$  for y position

can be achieved by  
the sensor itself

from external tracker

# Time resolution in large area AC-LGAD strip sensor :

10 mm length, 500  $\mu\text{m}$  pitch, 50  $\mu\text{m}$  metal width, 50  $\mu\text{m}$  thickness, 1600  $\Omega/\square$  resistivity, and 240  $\text{pF}/\text{mm}^2$  capacitance



- Without delay correction, the time resolution  $\sim 45 - 55$  ps
- Adding the tracker-based delay corrections improves the resolution to  $\sim 35 - 42$  ps
- Using multi-channel timestamp with delay correction, time resolution  $\sim 34$  ps (almost uniform across surface)

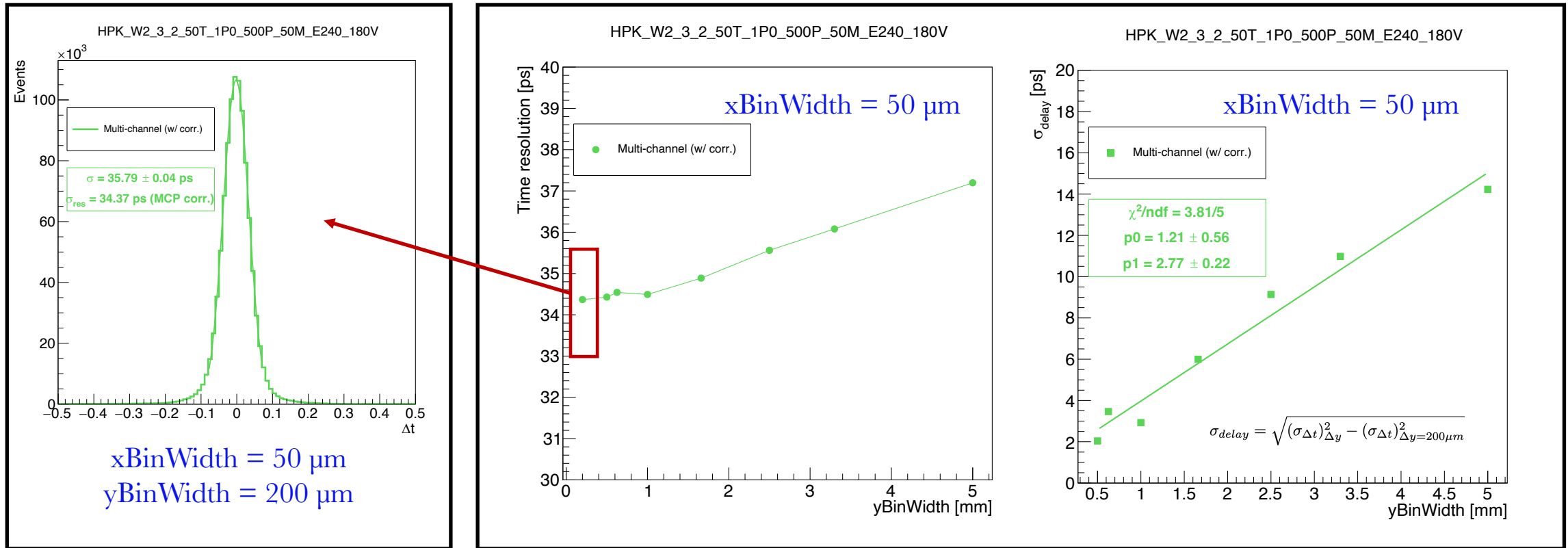
Multi-channel time stamp,

$$t_{\text{reco}} = \frac{a_1^2 t_1 + a_2^2 t_2}{a_1^2 + a_2^2}$$



# Impact of delay map resolution on time resolution in large area AC-LGAD strip sensor :

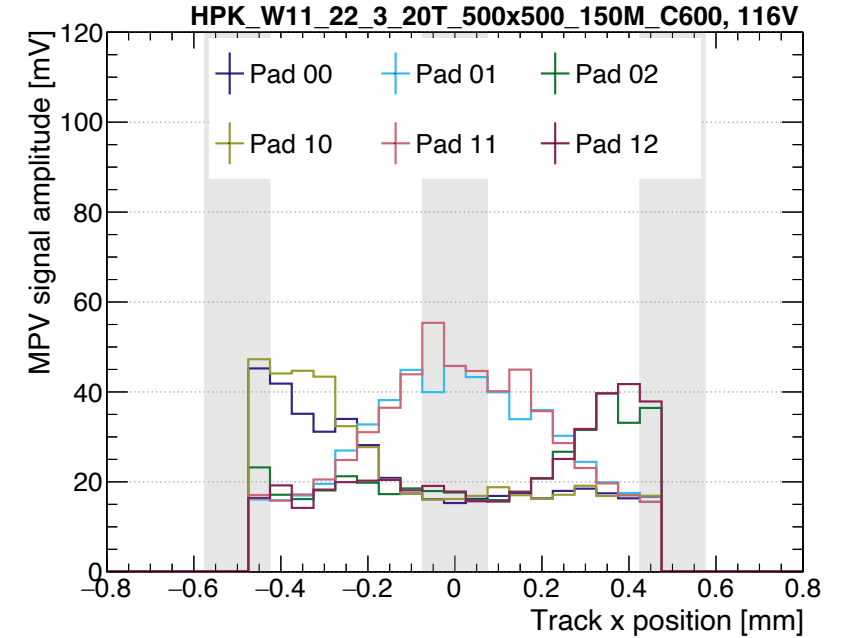
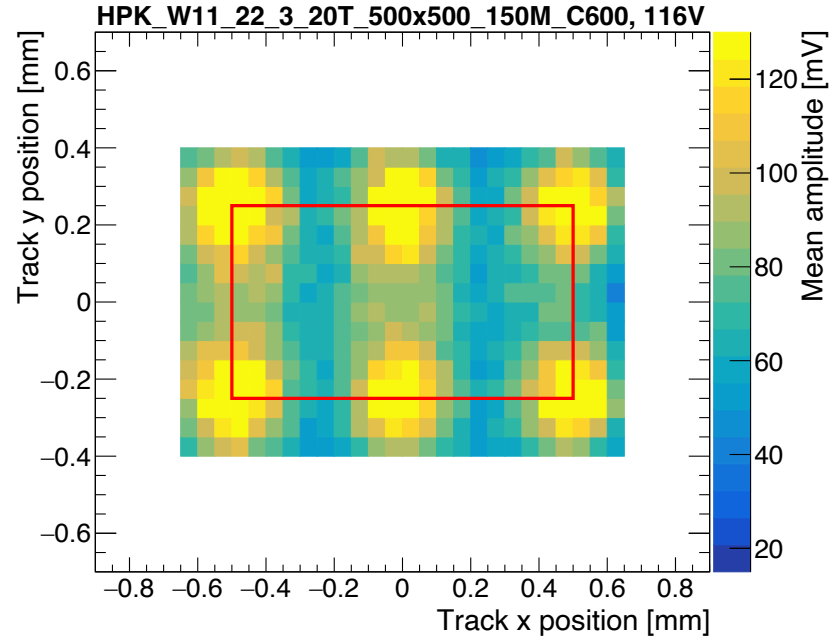
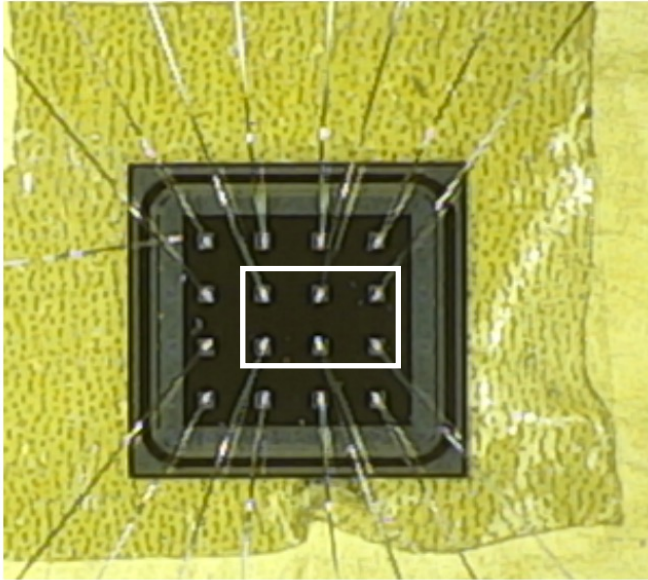
10 mm length, 500  $\mu\text{m}$  pitch, 50  $\mu\text{m}$  metal width, 50  $\mu\text{m}$  thickness, 1600  $\Omega/\square$  resistivity, and 240  $\text{pF}/\text{mm}^2$  capacitance



- Delay contribution in the time resolution increases with increasing yBinwidth in delay map along the direction of the strips
- Negligible change in time resolution until yBinwidth = 1.5 mm, and a change of  $\sim 2\text{ps}$  at yBinwidth = 5 mm (half of the strip length)

# Large area AC-LGAD pixel sensor :

500 × 500 μm pitch, 20 μm thickness, 150 μm metal width, 400 Ω/□ resistivity, and 600 pF/mm<sup>2</sup> capacitance

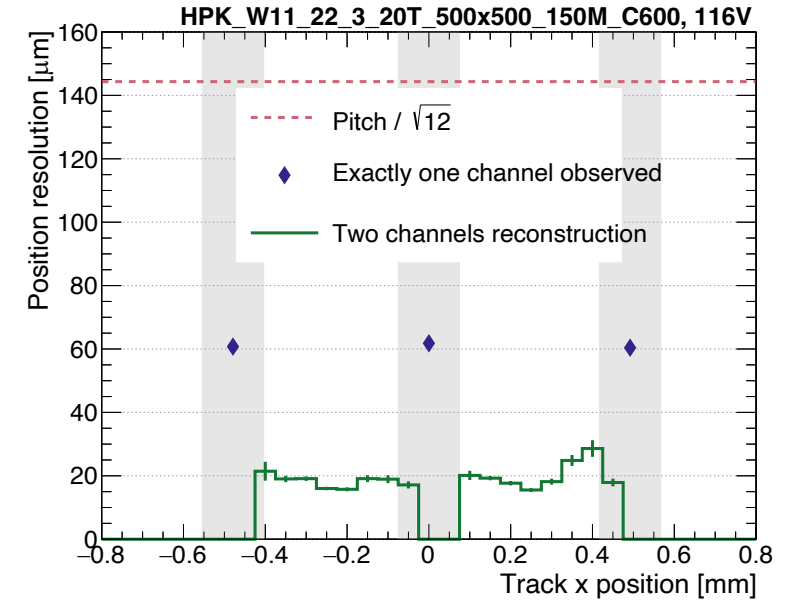
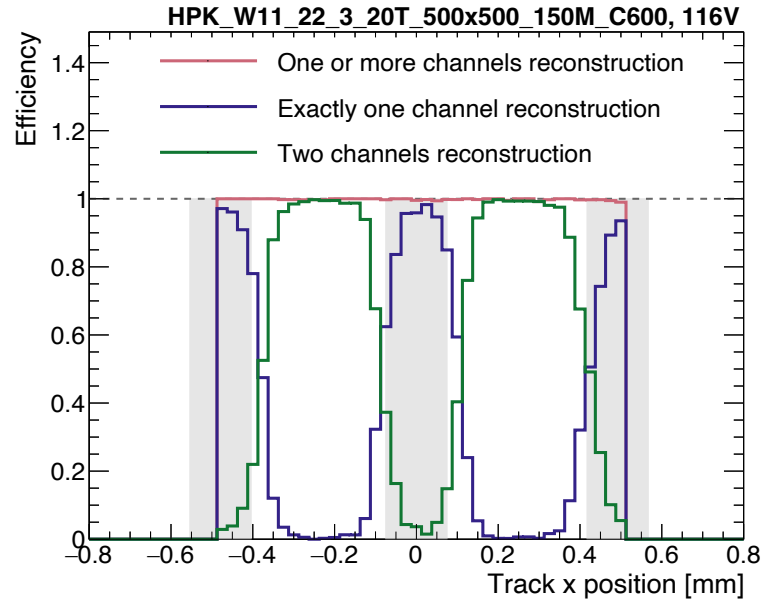
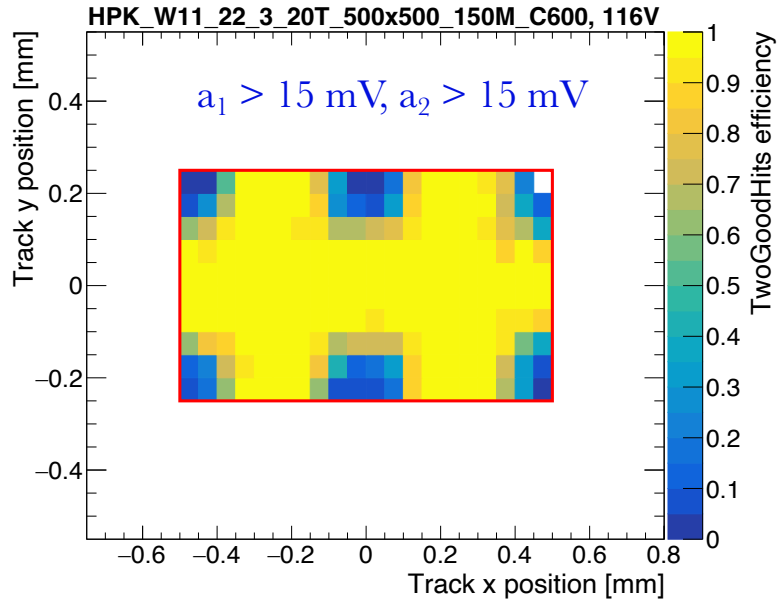


- Signal sharing between pads enables the position reconstruction in both direction (x and y)
- Significantly smaller charge sharing in the metal pad limits the two-channel reconstruction
- Threshold of 15 mV on amplitude for leading and sub-leading channels to qualify for two-channel reconstruction

(\*) the gray box only represents the location of metal pad; it also contain the gap region between metal pads in same column

# Spatial resolution in large area AC-LGAD pixel sensor :

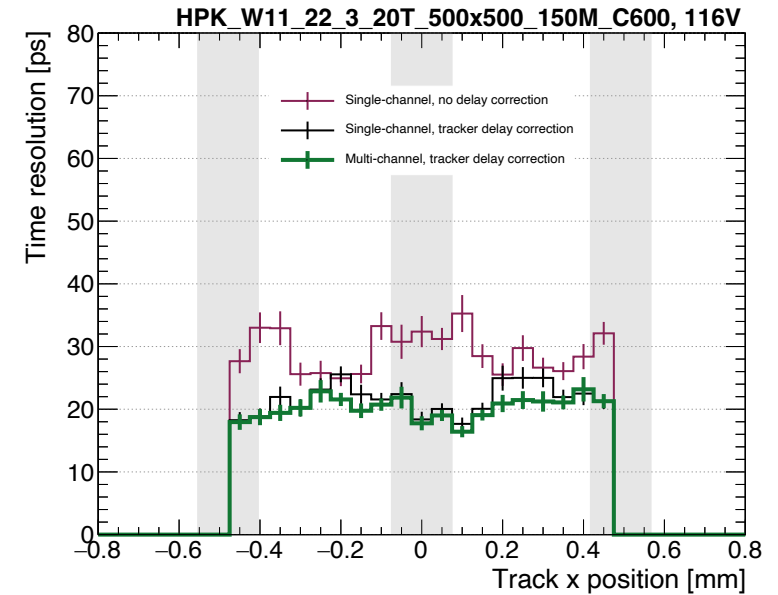
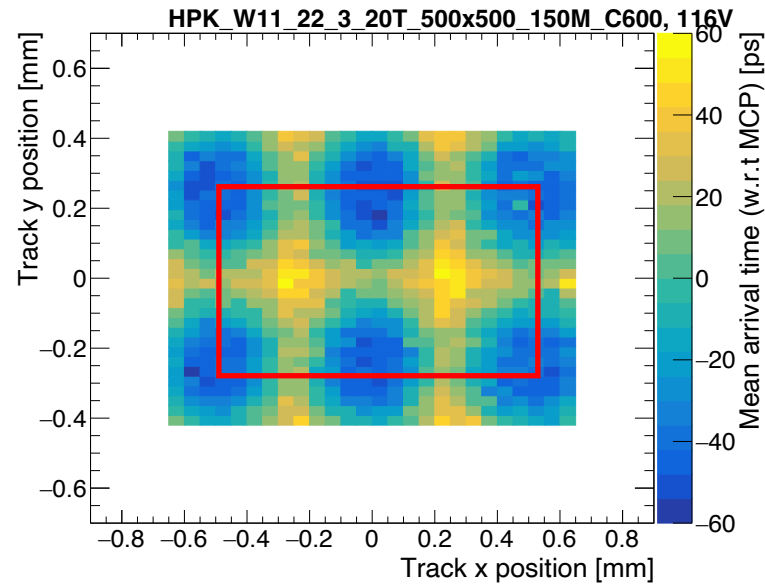
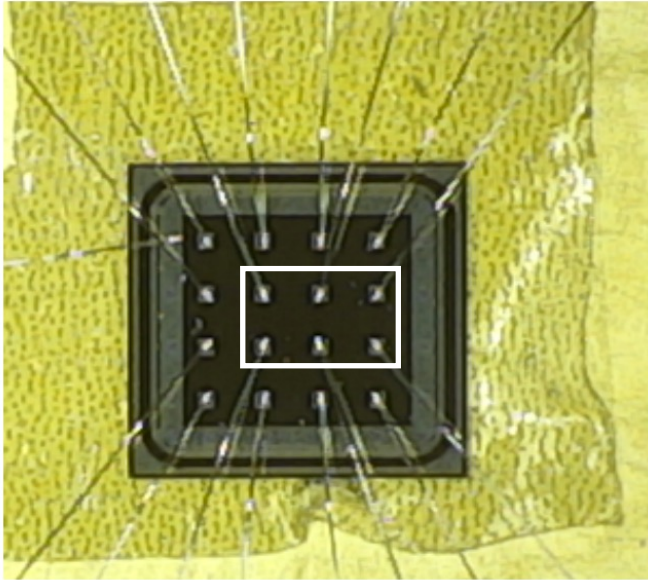
500 × 500 μm pitch, 20 μm thickness, 150 μm metal width, 400 Ω/□ resistivity, and 600 pF/mm<sup>2</sup> capacitance



- For each event, the amplitude from two channels in column has been added to enhance the charge sharing in gap regions
- Two-channel efficiency  $\sim 1$  in mid gap region and suffers in and near metal pad region
- Two-channel position resolution  $\sim 20 \mu\text{m}$
- Position resolution in metal pads ( $\sim 60 \mu\text{m}$ ) can be improved by further reducing the metal pad width

# Time resolution in large area AC-LGAD pixel sensor :

500 × 500 μm pitch, 20 μm thickness, 150 μm metal width, 400 Ω/□ resistivity, and 600 pF/mm<sup>2</sup> capacitance



- Delay map use the resolution of 50 μm for x position and 50 μm for y position
- Without delay correction, the time resolution ~ 30 ps
- Adding the tracker-based delay corrections improves the resolution to ~ 20 ps
- Using multi-channel timestamp with delay correction, time resolution ~ 20 ps

can be achieved by  
the sensor itself

# Summary :

- In strip sensor,
  - x resolution (perpendicular to the strip direction -  $\phi$  direction in lab frame) of delay map for correction be achieved by the sensor itself
  - For y resolution (along the strip direction - z direction in lab frame) of delay map, need to rely on external tracker with a reasonable resolution
    - negligible change in time resolution until  $y\text{Binwidth} = 1.5 \text{ mm}$ , and an increase of  $\sim 2.5 \text{ ps}$  from 34.5 to 37 ps with  $y\text{Binwidth} = 5 \text{ mm}$
- In pixel sensor (metal width of  $150 \mu\text{m}$ ),
  - x and y resolution (along x and y direction in lab frame) of delay map for correction be achieved by the sensor itself

Extra slides:

## AC-LGAD team:

**Fermilab:** Christopher Madrid, Irene Dutta, Artur Apresyan, Sergey Los, Cristián Peña, Si Xie

**BNL:** Wei Chen, Gabriele Giacomini, Alessandro Tricoli, Gabriele D'Amen, Enrico Rossi

**LBNL:** Ryan Heller, Zhenyu Ye

**Caltech:** Si Xie

**Universidad Técnica Federico Santa María:** Claudio San Martín, William K. Brooks, Matías Barría

**University of Illinois at Chicago:** Shirsendu Nanda, Danush Shekar, Zhenyu Ye

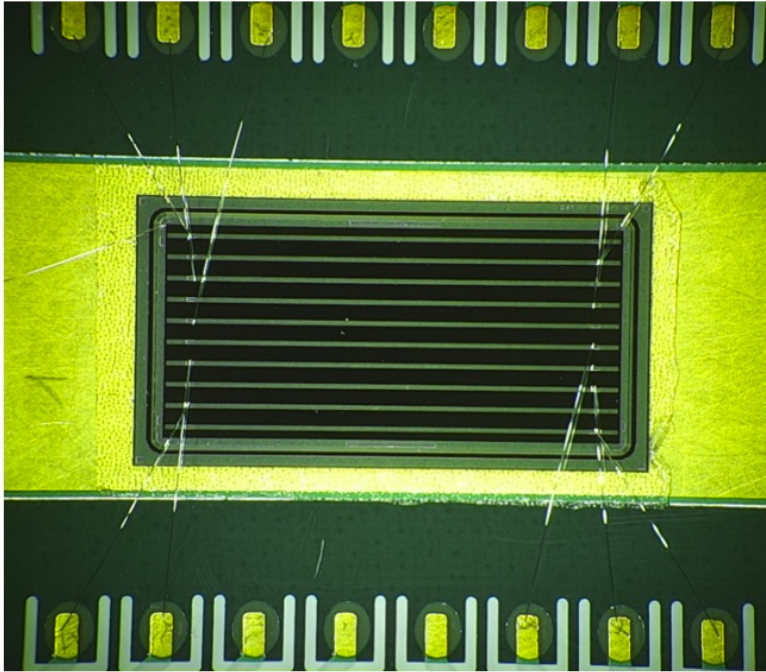
**The University of Iowa:** Ohannes Kamer Köseyan

**Yerevan Physics Institute:** Aram Hayrapetyan

\*The work is supported in part by the Office of Nuclear Physics within the U.S. DOE Office of Science through grant No. DE-FG02-94ER40865 and the University of Illinois at Chicago.

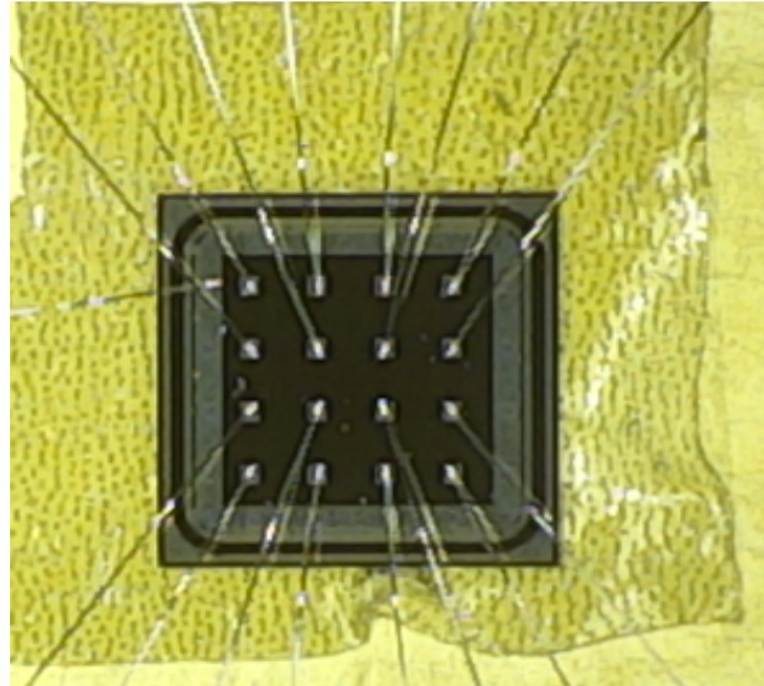
# Large area AC-LGAD sensors in test beam campaign 2023:

## HPK strip sensor



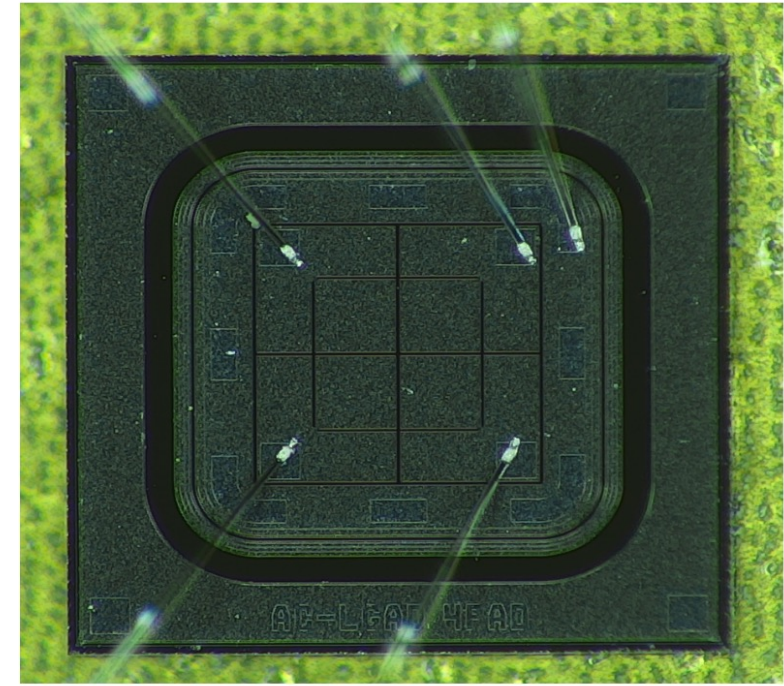
10 mm length, 500  $\mu\text{m}$  pitch, 50  $\mu\text{m}$  metal width, 50  $\mu\text{m}$  thickness, 1600  $\Omega/\square$  resistivity, and 240 pF/mm<sup>2</sup> capacitance

## HPK 4 × 4 pixel sensor



500 × 500  $\mu\text{m}$  pitch, 20  $\mu\text{m}$  thickness, 150  $\mu\text{m}$  metal width, 400  $\Omega/\square$  resistivity, and 600 pF/mm<sup>2</sup> capacitance

## HPK 2 × 2 pixel sensor

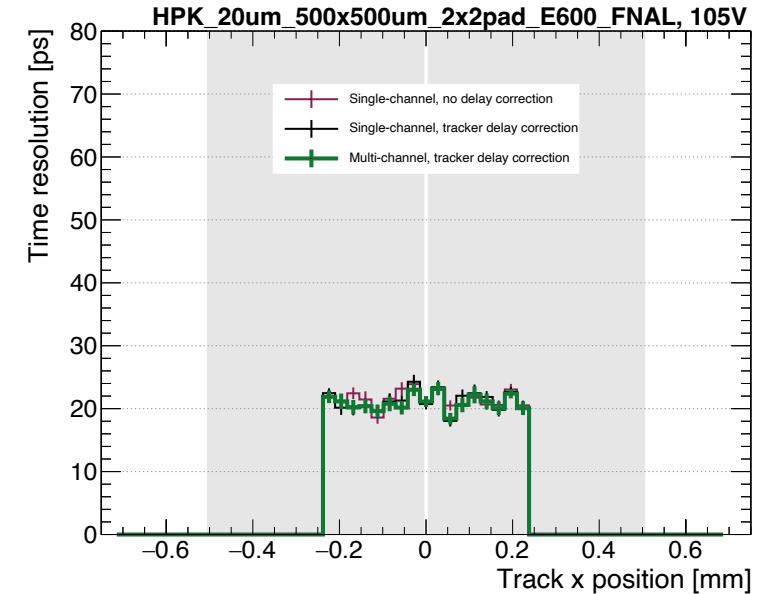
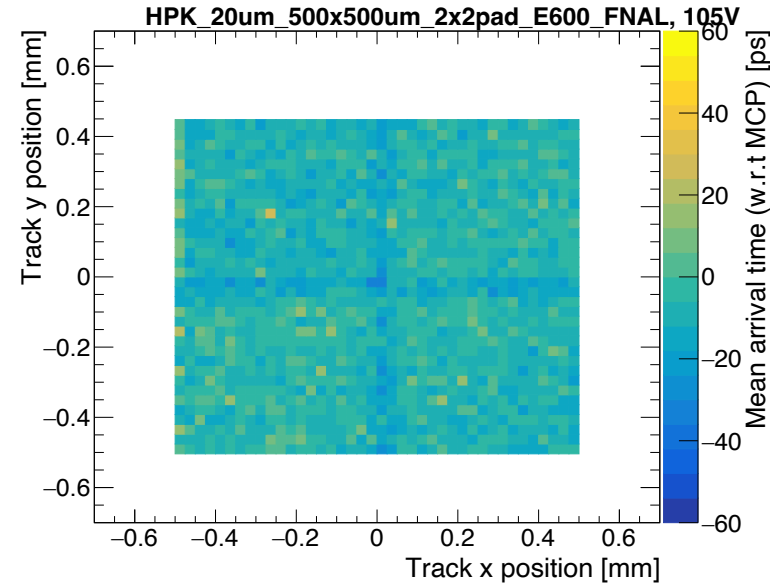
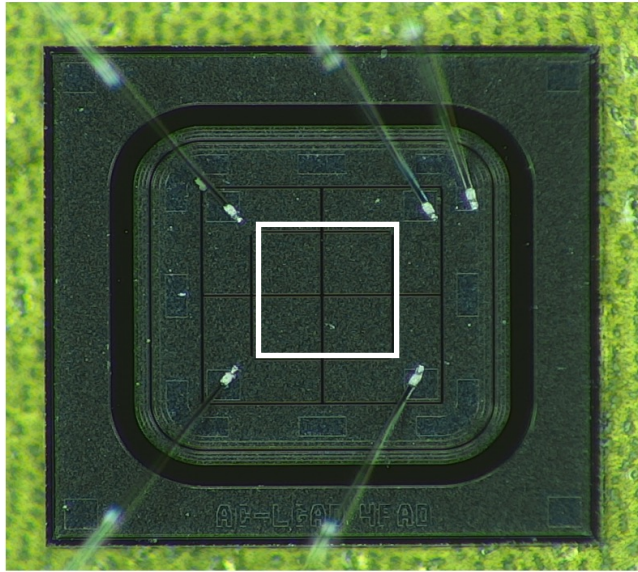


500 × 500  $\mu\text{m}$  pitch, 20  $\mu\text{m}$  thickness, 450  $\mu\text{m}$  metal width, 1600  $\Omega/\square$  resistivity, and 600 pF/mm<sup>2</sup> capacitance



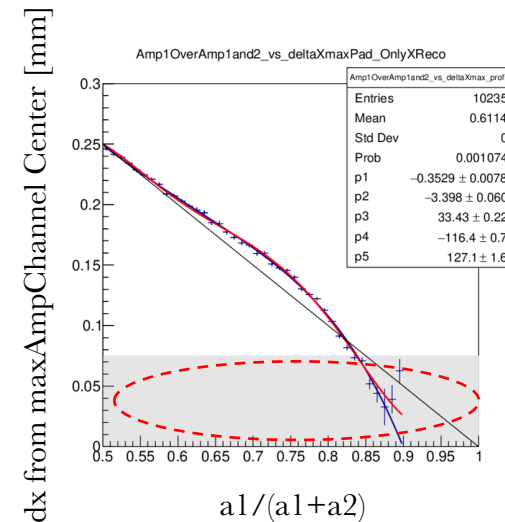
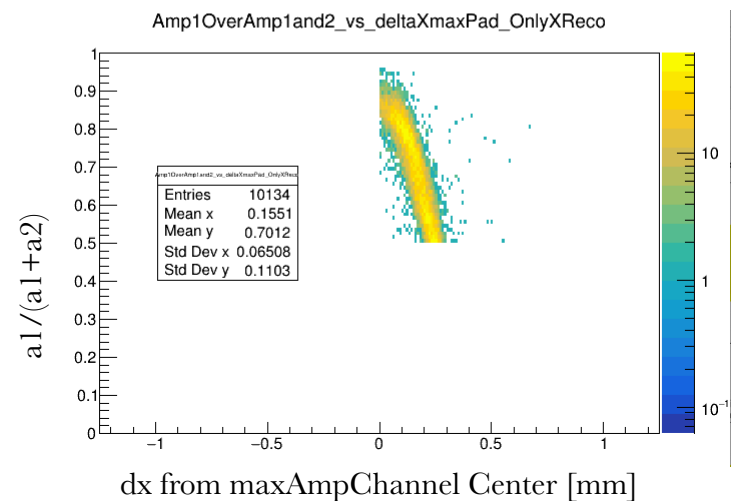
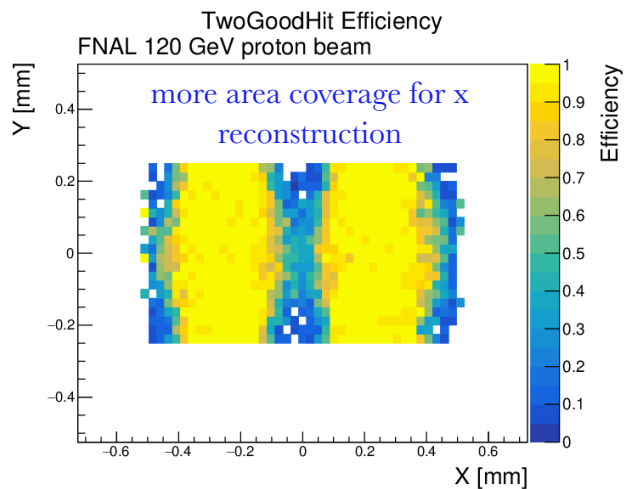
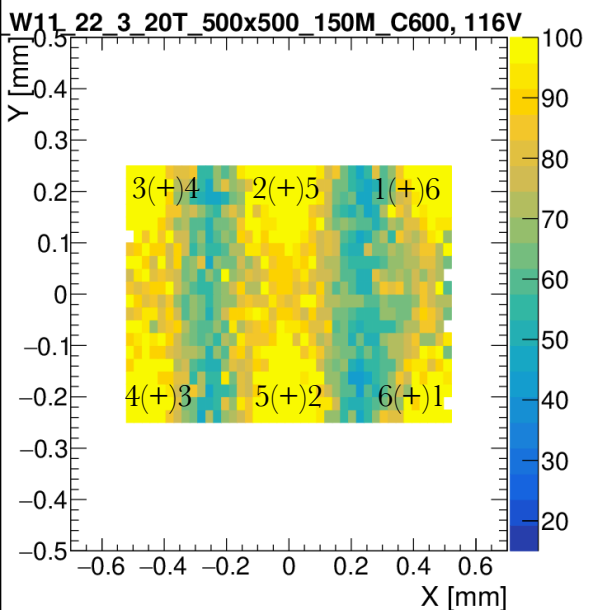
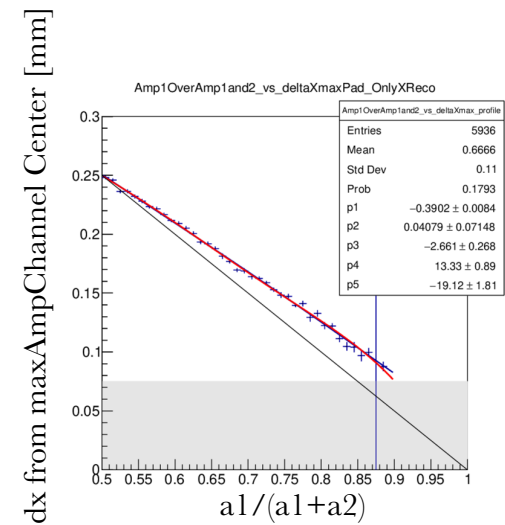
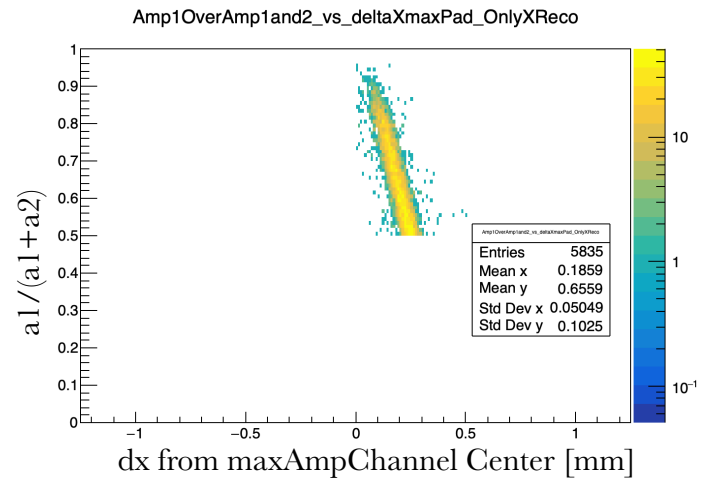
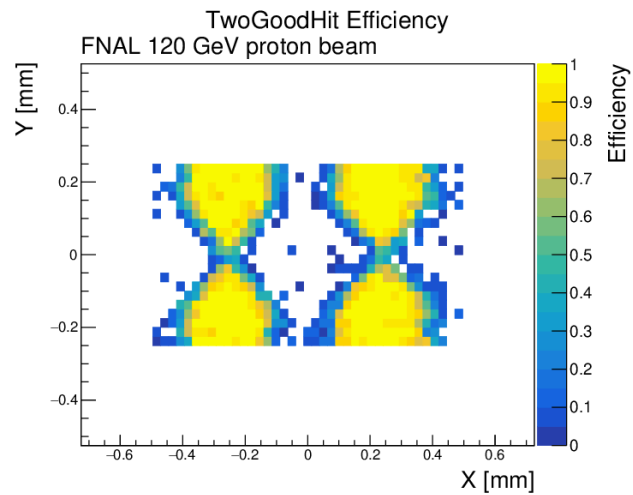
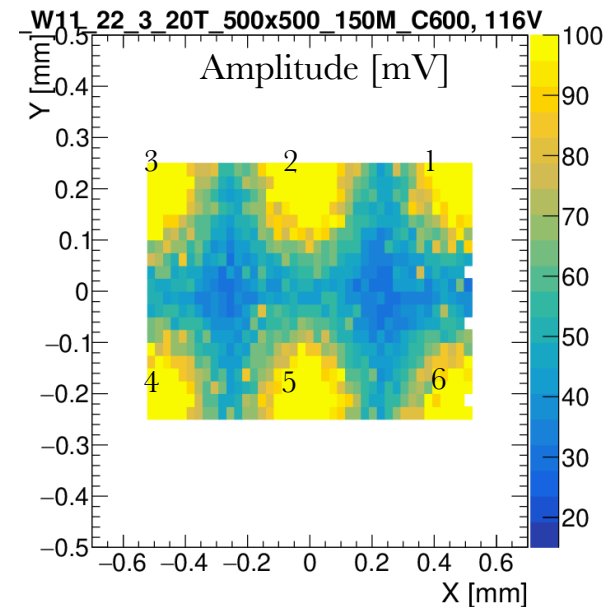
# Time resolution in large area AC-LGAD (2 x 2) pixel sensor :

500 × 500 μm pitch, 20 μm thickness, **450 μm metal width**, 1600 Ω/□ resistivity, and 600 pF/mm<sup>2</sup> capacitance



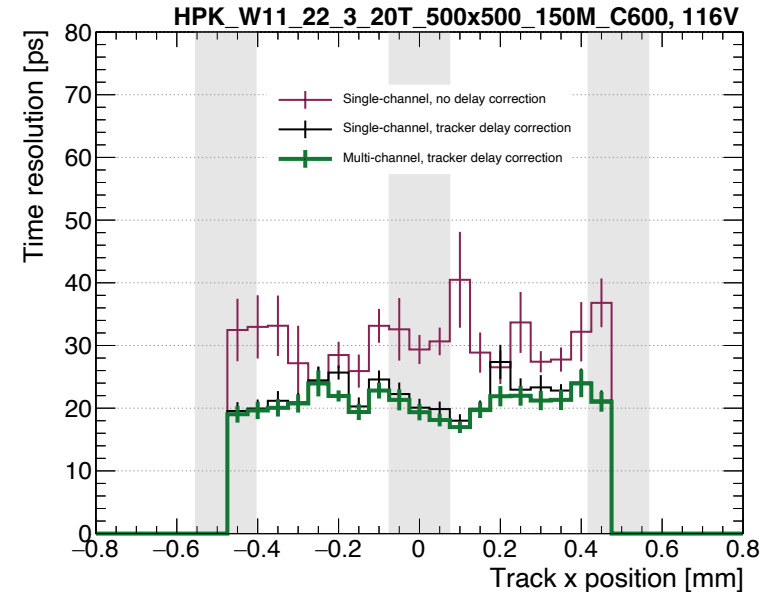
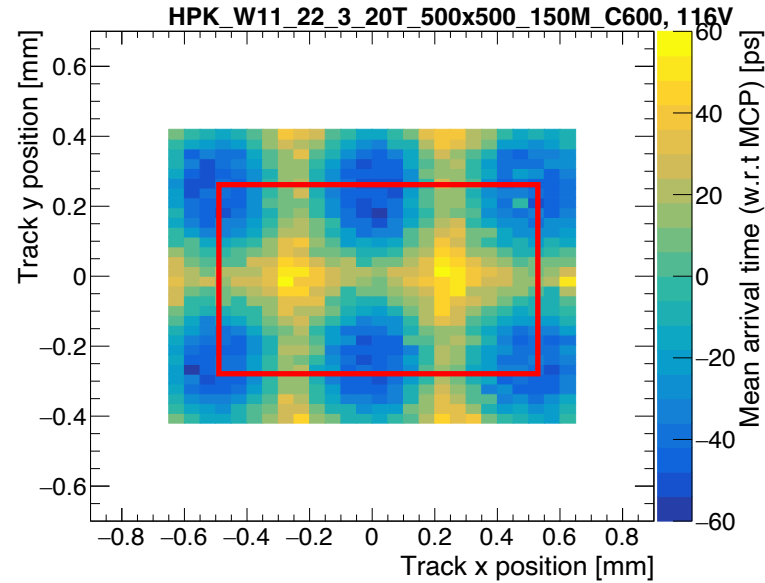
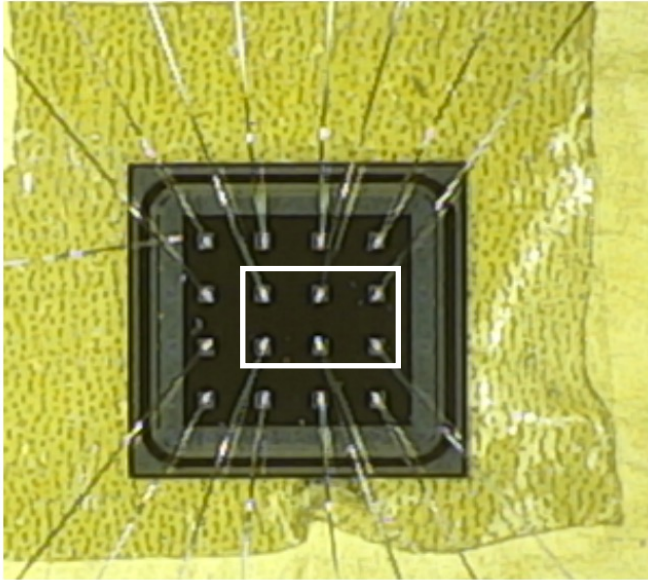
- Mean arrival time for the signal is significantly small  $O(10 \text{ ps})$
- Delay map use the resolution of 50 μm for x position and 50 μm for y position
- No significant improvement using the delay map correction
- Time resolution  $\sim 20 \text{ ps}$  (almost uniform across surface)

# x position reconstruction in pixel sensor:



# Time resolution in large area AC-LGAD pixel sensor :

500 × 500 μm pitch, 20 μm thickness, 150 μm metal width, 400 Ω/□ resistivity, and 600 pF/mm<sup>2</sup> capacitance



- Delay map use the resolution of 50 μm for x position and 50 μm for y position
- Without delay correction, the time resolution ~ 30 ps
- Adding the tracker-based delay corrections improves the resolution to ~ 20 ps
- Using multi-channel timestamp with delay correction, time resolution ~ 20 ps

can be achieved by  
the sensor itself